Application No. 09/914,456

Filed: August 28, 2001

TC Art Unit: 2623

Confirmation No.: 5339

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph on page 1, line 26, to page 2,

line 11, as follows:

The high accuracy metrology of test specimens, such as the

topographic measurement of bow, warp, flatness, thickness etc. of

such objects as semiconductor wafers, magnetic disks and the like,

is impeded by the presence of noise in the output data. Depending

on the inherent properties of the instrument and the environment,

the data may have a noise content that displays larger peak to

peak magnitude that than the actual dimensions being measured. It

is difficult to remove all sources of wafer vibration in a sensor

based dimensional metrology system when the wafer moves between

the sensors. The natural frequency of wafer vibration is of the

order of tens to a few hundred Hertz, depending on wafer size and

loading conditions, and the observed pattern of vibration has a

spatial wavelength less than a few mm. If this noise is not

removed, it directly affects the repeatability and reproducibility

of the measurements of the system.

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